



PJM2319PSA

P-Enhancement Field Effect Transistor

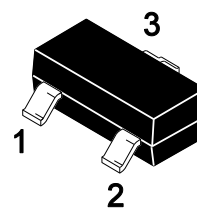
Features

- Fast Switching
- Ultra Low Qgd
- $R_{DS(on)} \leq 80 \text{ m}\Omega @ V_{GS} = -10\text{V}$

Application

- Load Switch
- DC/DC Converter

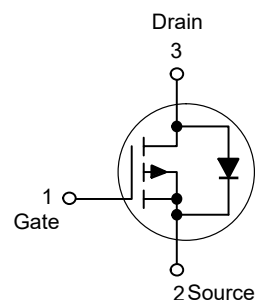
SOT-23



1. Gate 2. Source 3. Drain

Marking: S19

Schematic Diagram



Absolute Maximum Ratings

Ratings at $T_A = 25^\circ\text{C}$ unless otherwise specified.

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$-V_{DS}$	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$-I_D$	$T_C = 25^\circ\text{C}$	4.4
		$T_A = 25^\circ\text{C}$	3.1
Pulsed Drain Current ^{Note 1}	$-I_{DM}$	20	A
Total Power Dissipation	P_D	1.25	W
Operating Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	- 55 to + 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Units
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	100	$^\circ\text{C/W}$



PJM2319PSA

P-Enhancement Field Effect Transistor

Electrical Characteristics

Ratings at $T_J = 25^\circ\text{C}$ unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-to-Source Breakdown Voltage	$-BV_{DSS}$	$V_{GS} = 0\text{ V}, I_D = -250\mu\text{A}$	40	-	-	V
Zero Gate Voltage Drain Current	$-I_{DSS}$	$V_{DS} = -40\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	μA
Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	-	-	± 100	nA
Gate Threshold Voltage ^{Note2}	$-V_{GS(th)}$	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	1	-	3	V
Drain-to-Source On-Resistance ^{Note2}	$R_{DS(on)}$	$V_{GS} = -10\text{ V}, I_D = -3.1\text{ A}$	-	66	80	m Ω
		$V_{GS} = -4.5\text{ V}, I_D = -2.6\text{ A}$	-	90	120	
Forward Transconductance ^{Note2}	g_{FS}	$V_{DS} = -15\text{ V}, I_D = -3.1\text{ A}$	-	10	-	S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}, V_{DS} = -20\text{ V}$	-	595	-	pF
Output Capacitance	C_{oss}		-	76	-	
Reverse Transfer Capacitance	C_{rss}		-	61	-	
Total Gate Charge	Q_g	$V_{DS} = -20\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -3.1\text{ A}$	-	7	11	nC
Gate-Source Charge	Q_{gs}		-	2.5	-	
Gate-Drain Charge	Q_{gd}		-	3.2	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = -20\text{ V}, I_D = -2.5\text{ A}, V_{GEN} = -10\text{ V}, R_L = 8\Omega,$	-	8	16	ns
Turn-On Rise Time	t_r		-	9	18	
Turn-Off Delay Time	$t_{d(off)}$		-	20	30	
Turn-Off Fall Time	t_f		-	8	16	
Source-Drain Diode Characteristics						
Body Diode Voltage	$-V_{SD}$	$I_S = -2.5\text{ A}, V_{GS} = 0\text{ V}$	-	0.8	1.5	V
Continuous Source-Drain Diode Current	$-I_S$		--	--	1	A

Notes:

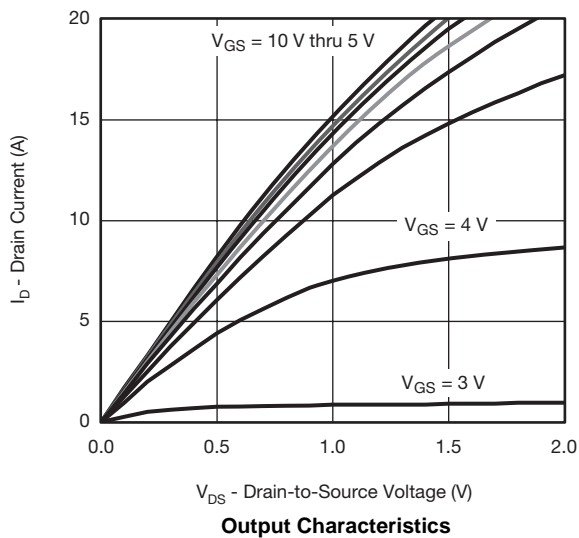
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.



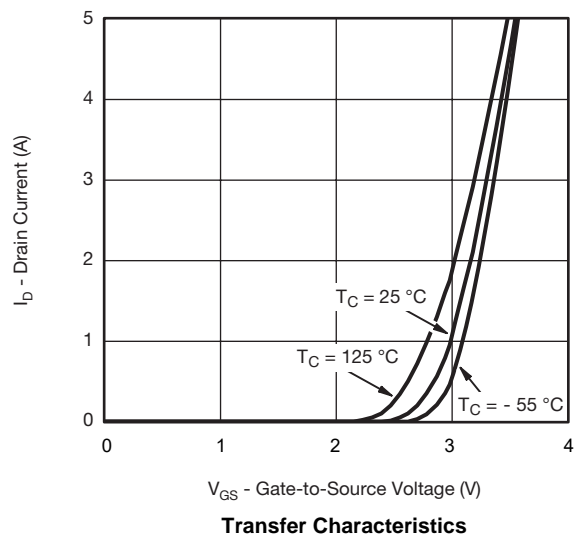
PJM2319PSA

P-Enhancement Field Effect Transistor

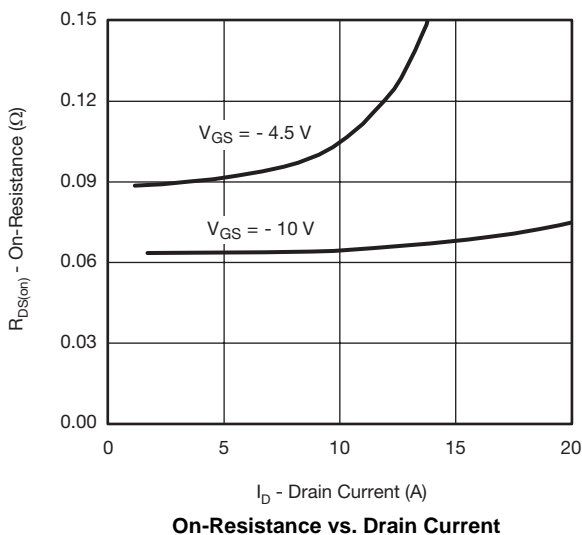
Ratings and Characteristic Curves



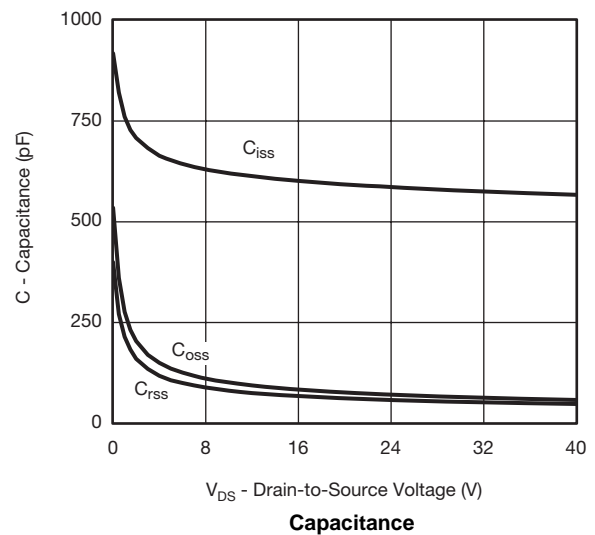
Output Characteristics



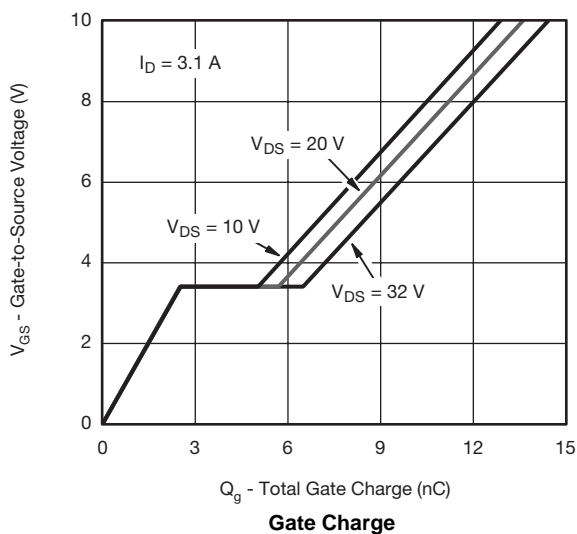
Transfer Characteristics



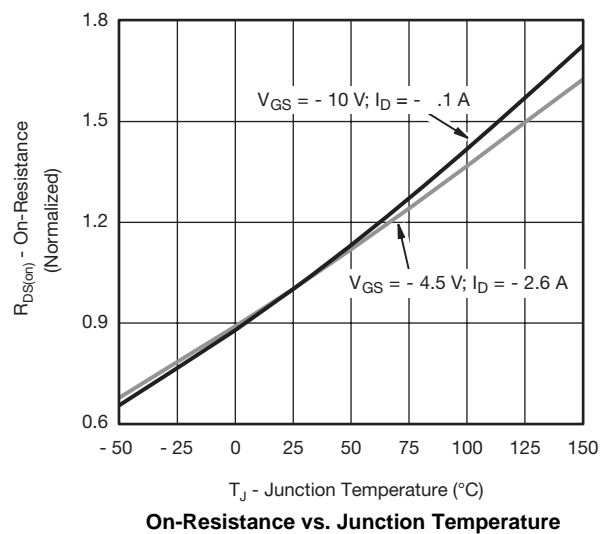
On-Resistance vs. Drain Current



Capacitance



Gate Charge

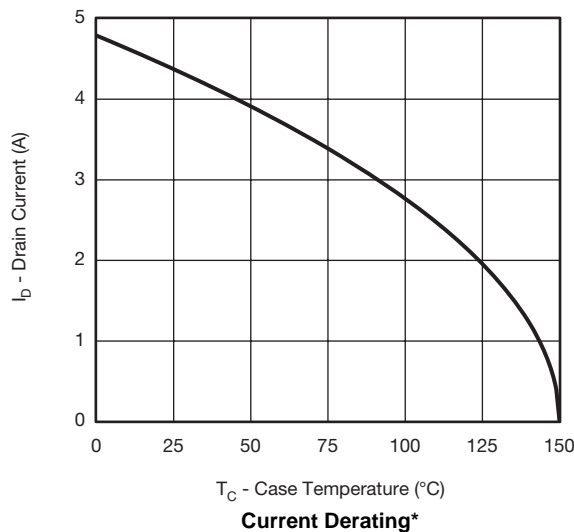
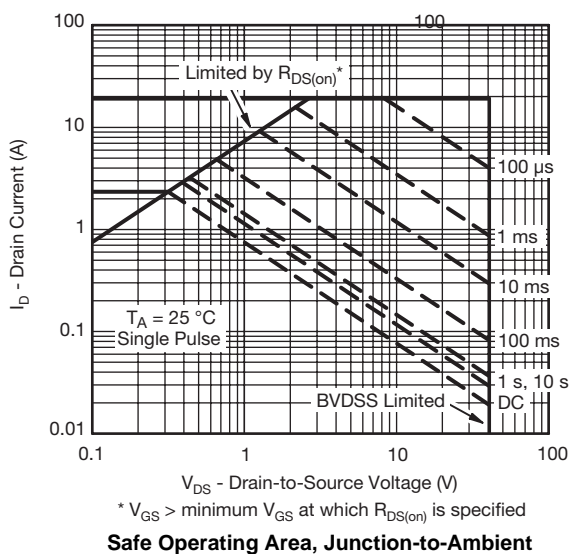
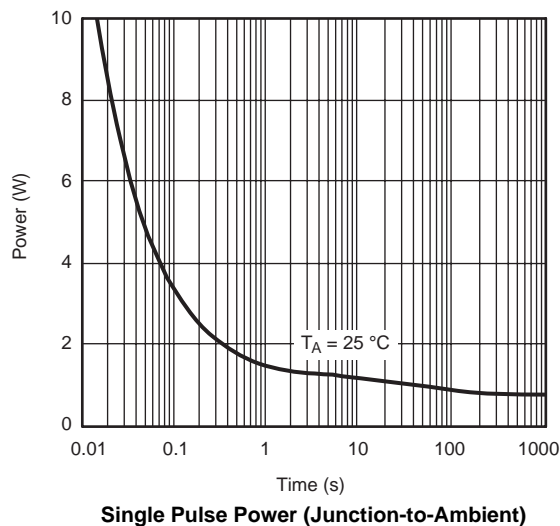
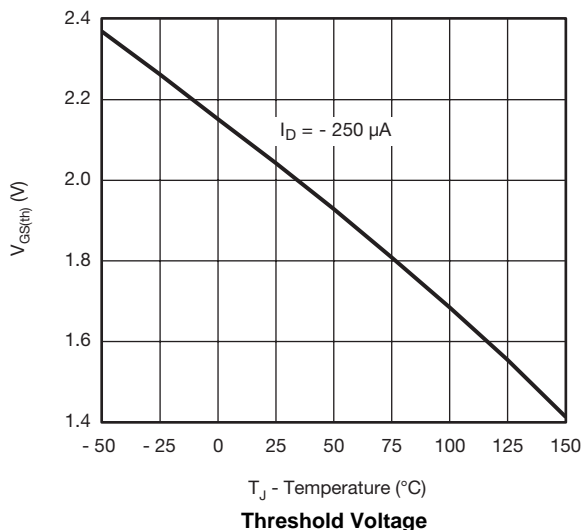
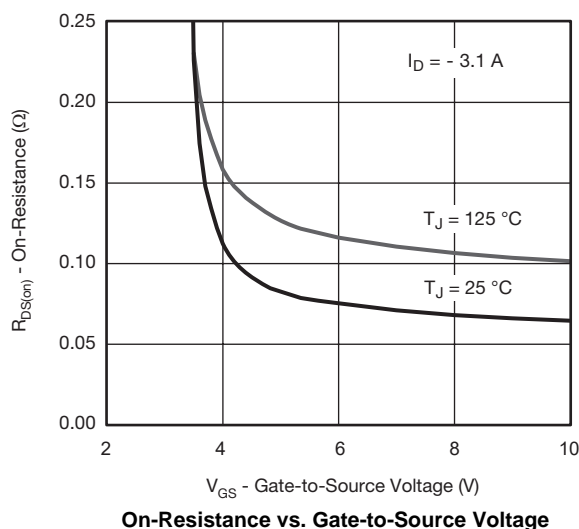
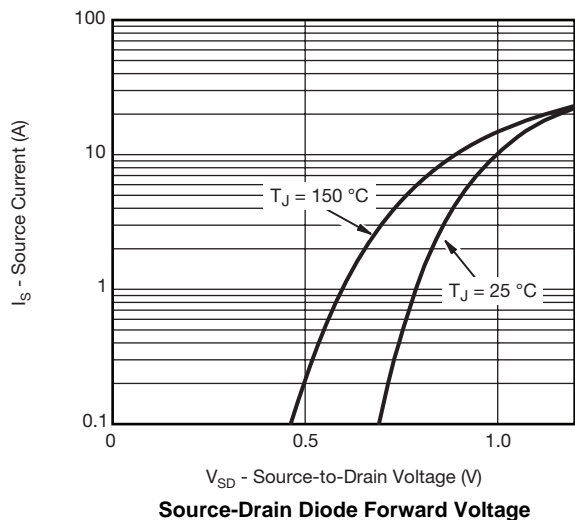


On-Resistance vs. Junction Temperature



PJM2319PSA

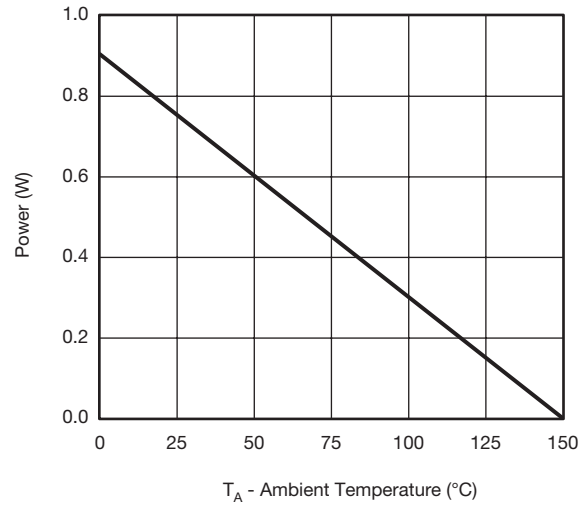
P-Enhancement Field Effect Transistor



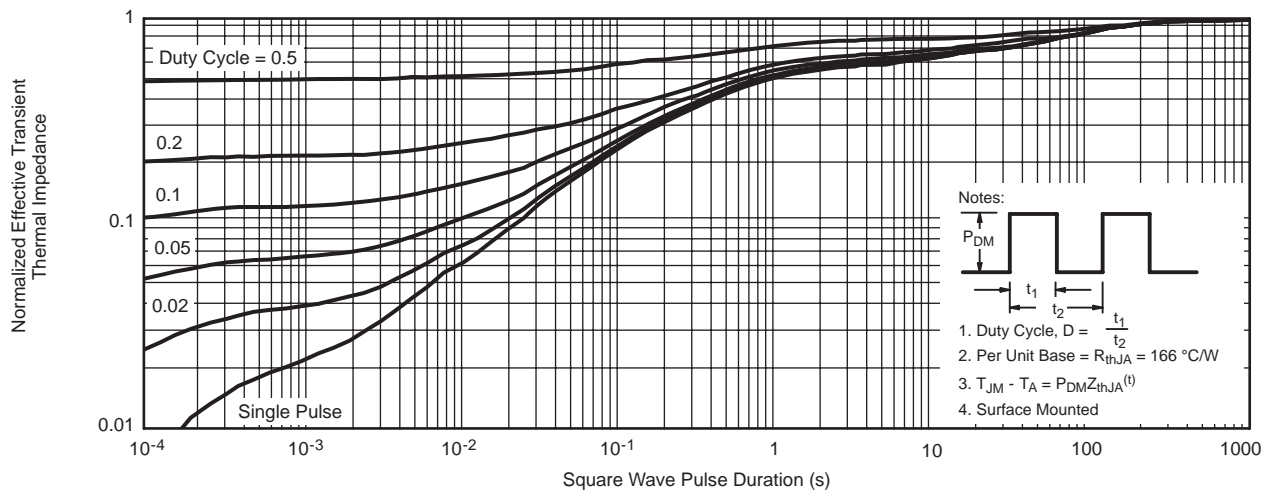


PJM2319PSA

P-Enhancement Field Effect Transistor



Power (stead-state), Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient

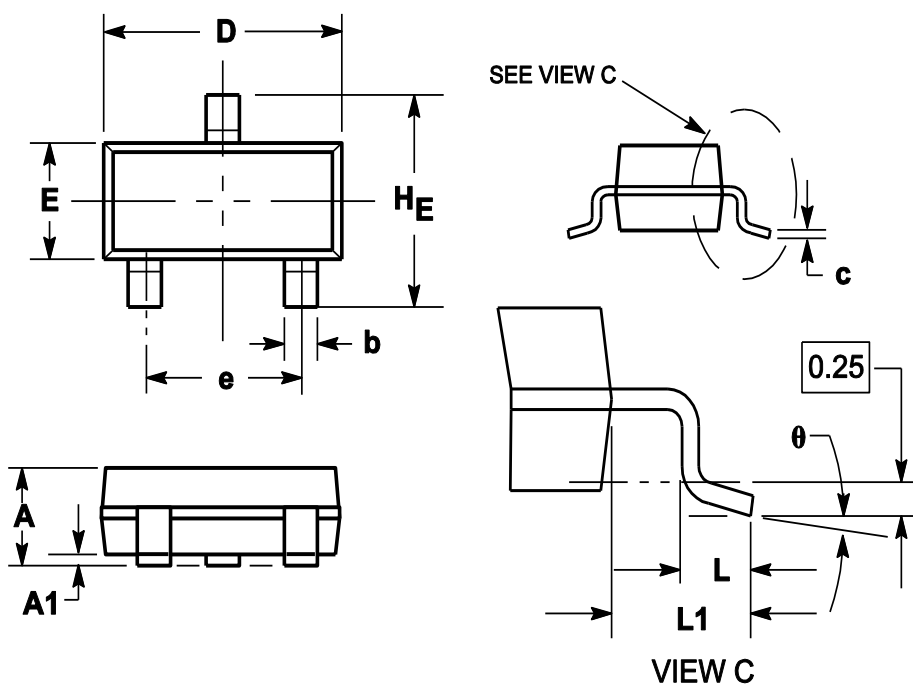


PJM2319PSA

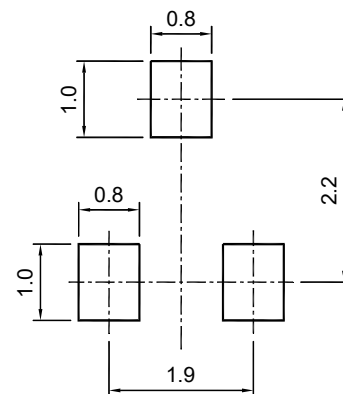
P-Enhancement Field Effect Transistor

Package Outline

SOT-23 (TO-236)



Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A	0.900	1.025	1.150
A1	0.000	0.050	0.100
b	0.300	0.400	0.500
c	0.080	0.115	0.150
D	2.800	2.900	3.000
E	1.200	1.300	1.400
HE	2.250	2.400	2.550
e	1.800	1.900	2.000
L1	0.550REF		
L	0.300		0.500
θ	0°		8°



SOT-23 (TO-236)

Recommended Soldering Pad

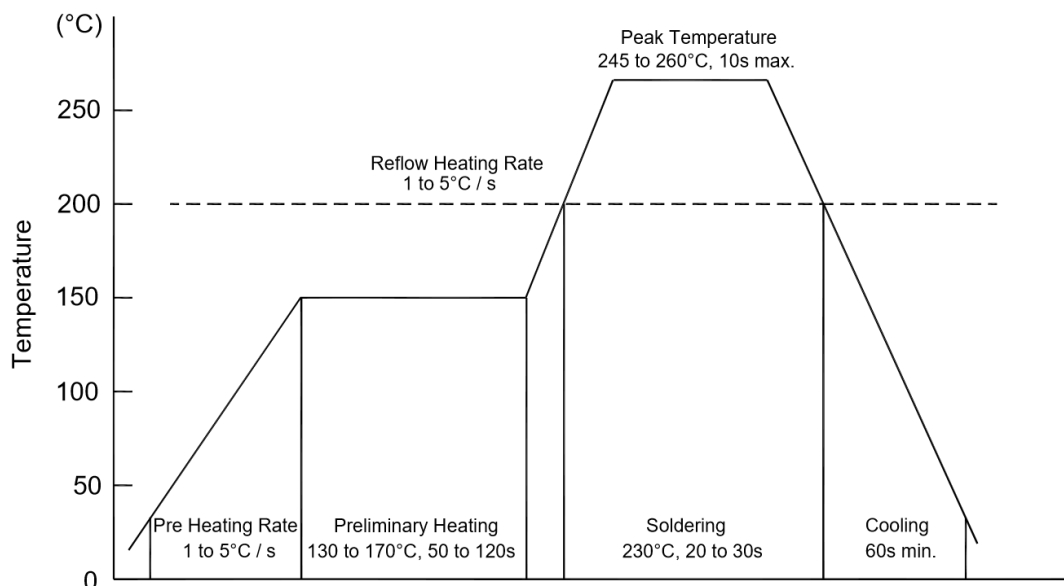
Ordering Information

Device	Package	Shipping
PJM2319PSA	SOT-23	3,000PCS/T&R (7 inch)



Conditions of Soldering And Storage

◆ Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters:

- Time length of peak temperature (longer)
- Time length of soldering (longer)
- Thickness of solder paste (thicker)

◆ Conditions of hand soldering

- Temperature: 370 °C
- Time: 3s max.
- Times: one time

◆ Storage conditions

- **Temperature**
5 to 40 °C
- **Humidity**
30 to 80% RH
- **Recommended period**
One year after manufacturing

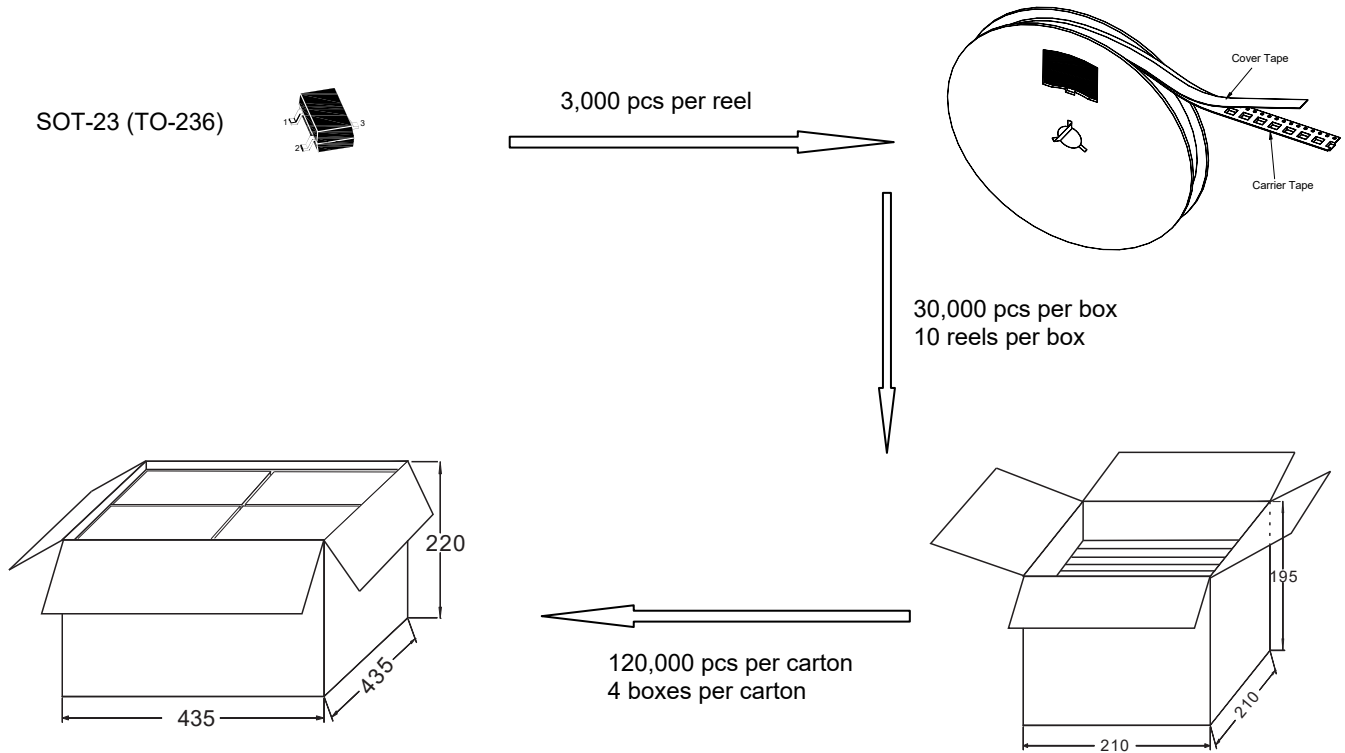


PJM2319PSA

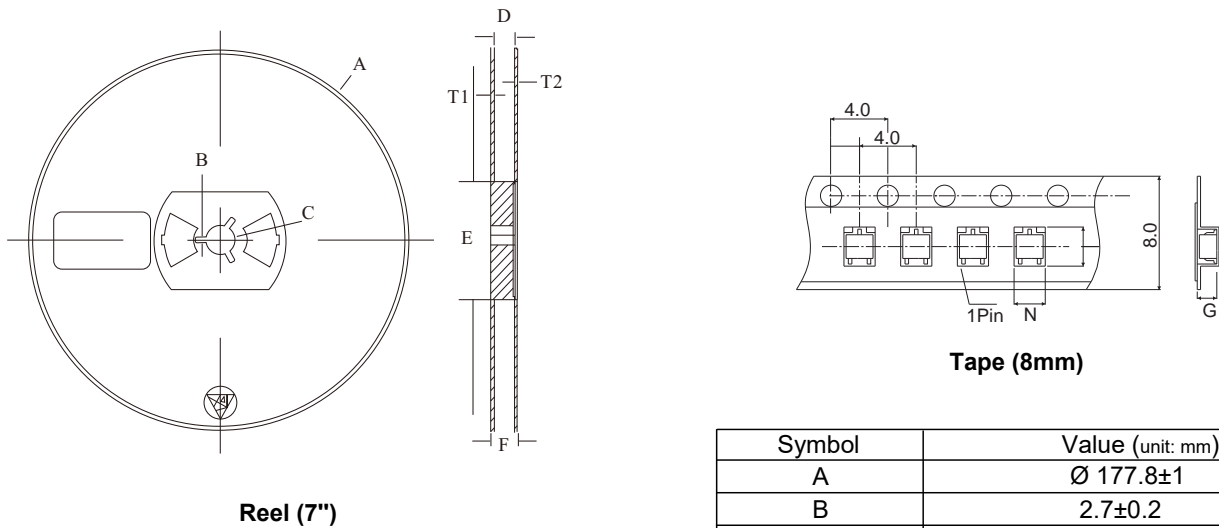
P- Enhancement Mode Field Effect Transistor

Package Specifications

◆ The method of packaging



◆ Embossed tape and reel data



Symbol	Value (unit: mm)
A	∅ 177.8±1
B	2.7±0.2
C	∅ 13.5±0.2
E	∅ 54.5±0.2
F	12.3±0.3
D	9.6+2/-0.3
T1	1.0±0.2
T2	1.2±0.2
N	3.15±0.1
G	1.25±0.1

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [MOSFET](#) category:

Click to view products by [Pingjingsemi](#) manufacturer:

Other Similar products are found below :

[614233C](#) [648584F](#) [MCH3443-TL-E](#) [MCH6422-TL-E](#) [FDPF9N50NZ](#) [FW216A-TL-2W](#) [FW231A-TL-E](#) [APT5010JVR](#) [NTNS3A92PZT5G](#)
[IRF100S201](#) [JANTX2N5237](#) [2SK2464-TL-E](#) [2SK3818-DL-E](#) [FCA20N60_F109](#) [FDZ595PZ](#) [STD6600NT4G](#) [FSS804-TL-E](#) [2SJ277-DL-E](#)
[2SK1691-DL-E](#) [2SK2545\(Q,T\)](#) [D2294UK](#) [405094E](#) [423220D](#) [MCH6646-TL-E](#) [TPCC8103,L1Q\(CM](#) [367-8430-0972-503](#) [VN1206L](#)
[424134F](#) [026935X](#) [051075F](#) [SBVS138LT1G](#) [614234A](#) [715780A](#) [NTNS3166NZT5G](#) [751625C](#) [873612G](#) [IRF7380TRHR](#)
[IPS70R2K0CEAKMA1](#) [RJK60S3DPP-E0#T2](#) [RJK60S5DPK-M0#T0](#) [APT5010JVFR](#) [APT12031JFLL](#) [APT12040JVR](#) [DMN3404LQ-7](#)
[NTE6400](#) [JANTX2N6796U](#) [JANTX2N6784U](#) [JANTXV2N5416U4](#) [SQM110N05-06L-GE3](#) [SIHF35N60E-GE3](#)